

General Description

The COP401L-R13 and COP410L-X13 should be used for exact emulation.

- Low cost
- Powerful instruction set
- 512 x 8 ROM, 32 x 4 RAM
- 15 I/O lines
- Two-Level subroutine stack
- 16 μ s instruction time
- Single supply operation (4.5V–8.3V)
- Low current drain (6 mA max.)
- Internal binary counter register with MICROWIRE™ serial I/O capability
- General purpose outputs
- High noise immunity inputs ($V_{IL}=1.2V$, $V_{IH}=3.6V$)
- Software/hardware compatible with other members of COP400 family
- Extended temperature range device COP313L (–40°C to +85°C)

The block diagram illustrates the internal architecture of the 6800 microprocessor. Key components include:

- Power and Ground:** VCC (pin 2) and GND (pin 10) are at the top. CKI (pin 18) and CKO (pin 15) are at the top right.
- Timing and Control:** A CLOCK GENERATOR feeds a DIVIDER, which produces the INSTRUCTION CLOCK (SYNC). A RESET LOGIC block (pin 17) is also shown.
- Memory and Registers:**
 - PROGRAM MEMORY (512 x 8 ROM) and ADDRESS are connected to the PC (Program Counter).
 - PC is connected to the 2 LEVEL STACK (SA, SB).
 - DIGIT ADDRESS DATA MEMORY (32 x 4 RAM) and REG ADDR IN are connected to the ACCUMULATOR A.
 - ACCUMULATOR A is connected to the ALU (Arithmetic Logic Unit).
 - ACCUMULATOR A is also connected to the CARRY (C) and SKL (Serial Keyboard/Lock) registers.
 - ACCUMULATOR A is connected to the D REGISTER (8 bits) and L DRIVERS.
- Serial I/O:** A SERIAL I/O REGISTER (SI03, SI02, SI01, SI00) is connected to the SKL register and the G REGISTER & BUFFER (G3, G2, G1, G0).
- External Connections:**
 - EN (pin 4) is connected to I/O CONTROLS.
 - SK (pin 8), SO (pin 8), and S1 (pin 7) are connected to the SKL register.
 - G3 (pin 14), G2 (pin 13), G1 (pin 12), and G0 (pin 11) are connected to the G REGISTER & BUFFER.
 - L7 (pin 18), L6 (pin 19), L5 (pin 20), L4 (pin 1), L3 (pin 3), L2 (pin 4), L1 (pin 5), and L0 (pin 6) are connected to the L DRIVERS.

TL/DD/8371-1

COP413L Absolute Maximum Ratings

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Voltage at Any Pin Relative to GND	−0.3 to +7V
Ambient Operating Temperature	0°C to +70°C
Ambient Storage Temperature	−65°C to +150°C
Lead Temp. (Soldering, 10 seconds)	300°C

Power Dissipation COP413L

0.3 Watt at 70°C

Total Source Current 25 mA

Total Sink Current 25 mA

Note: Absolute maximum ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications are not ensured when operating the device at absolute maximum ratings.

DC Electrical Characteristics 0°C ≤ T_A ≤ +70°C, 4.5V ≤ V_{CC} ≤ 6.3V unless otherwise noted.

Parameter	Conditions	Min	Max	Units
Standard Operating Voltage (V _{CC})	(Note 1)	4.5	6.3	V
Power Supply Ripple	Peak to Peak		0.4	V
Operating Supply Current	All Inputs and Outputs Open		6	mA
Input Voltage Levels				
CKI Input Levels				
Ceramic Resonator Input (÷8)				
Logic High (V _{IH})		3.0		V
Logic Low (V _{IL})			0.4	V
CKI (RC), Reset Input Levels	(Schmitt Trigger Input)			
Logic High		0.7 V _{CC}		V
Logic Low			0.6	V
SO Input Level (Test Mode)	(Note 2)	2.5		V
SI Input Level				
Logic High	(TTL Level)	2.0		V
Logic Low			0.8	V
L, G Inputs				
Logic High	(High Trip Levels)	3.6		V
Logic Low			1.2	V
Input Capacitance			7	pF
Reset Input Leakage		−1	+1	μA
Output Current Levels				
Output Sink Current				
SO and SK Outputs (I _{OL})	V _{OL} = 0.4V	0.9		mA
L0–L7 Outputs, G0–G3	V _{OL} = 0.4V	0.4		mA
CKO (I _{OL})	V _{OL} = 0.4V	0.2		mA
Output Source Current				
L0–L7 and G0–G3	V _{OH} = 2.4V	−25		μA
SO and SK Outputs (I _{OH})	V _{OH} = 1.0V	−1.2		mA
Push-Pull	V _{OH} = 2.4V	−25		μA
SI Input Load Source Current	V _{IL} = 0V	−10	−140	μA
Total Sink Current Allowed				
L7–L4, G Port			4	mA
L3–L0			4	mA
Any Other Pin			2.0	mA
Total Source Current Allowed				
Each Pin			1.5	mA

Note 1: V_{CC} voltage change must be less than 0.5V in a 1 ms period to maintain proper operation.

Note 2: SO output "0" level must be less than 0.8V for normal operation.

COP313L Absolute Maximum Ratings

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Voltage at Any Pin Relative to GND	−0.3 to +7V
Ambient Operating Temperature	−40°C to +85°C
Ambient Storage Temperature	−65°C to +150°C
Lead Temp. (Soldering, 10 seconds)	300°C

Power Dissipation COP313L

0.20 Watt at 85°C

Total Source Current

25 mA

Total Sink Current

25 mA

Note: Absolute maximum ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications are not ensured when operating the device at absolute maximum ratings.

DC Electrical Characteristics −40°C ≤ T_A ≤ +85°C, 4.5V ≤ V_{CC} ≤ 5.5V unless otherwise noted.

Parameter	Conditions	Min	Max	Units
Standard Operating Voltage (V _{CC})	(Note 1)	4.5	5.5	V
Power Supply Ripple	Peak to Peak		0.4	V
Operating Supply Current	All Inputs and Outputs Open		8	mA
Input Voltage Levels				
Ceramic Resonator Input (÷8)				
Logic High (V _{IH})		3.0		V
Logic Low (V _{IL})			0.3	V
CKI (RC), Reset Input Levels	(Schmitt Trigger Input)			
Logic High		0.7 V _{CC}		V
Logic Low			0.4	V
SO Input (Test Mode)	(Note 2)	2.5		V
SI Input Level				
Logic High	(TTL Level)	2.2		V
Logic Low			0.6	V
L, G Inputs				
Logic High	(High Trip Levels)	3.6		V
Logic Low			1.2	V
Input Capacitance			7	pF
Reset Input Leakage		−2	+2	μA
Output Current Levels				
Output Sink Current				
SO and SK Outputs (I _{OL})	V _{OL} = 0.4V	0.8		mA
L0–L7 Outputs, G0–G3 (I _{OL})	V _{OL} = 0.4V	0.4		mA
CKO (I _{OL})	V _{OL} = 0.4V	0.2		mA
Output Source Current				
L0–L7 and G0–G3	V _{OH} = 2.4V	−23		μA
SO and SK Outputs (I _{OH})	V _{OH} = 1.0V	−1.0		mA
(Push-Pull)	V _{OH} = 2.4V	−23		μA
SI Input Load Source Current	V _{IL} = 0V	−10	−200	μA
Total Sink Current Allowed				
L7–L4, G Port			4	mA
L3–L0			4	mA
Any Other Pin			1.5	mA
Total Source Current Allowed Each Pin			1.5	mA

Note 1: V_{CC} voltage change must be less than 0.5V in a 1 ms period to maintain proper operation.

Note 2: SO output "0" level must be less than 0.6V for normal operation.

AC Electrical Characteristics

COP413L: $0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C}$, $4.5\text{V} \leq V_{CC} \leq 6.3\text{V}$
 COP313L: $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$, $4.5\text{V} \leq V_{CC} \leq 5.5\text{V}$

Parameter	Conditions	Min	Max	Units
Instruction Cycle Time - t_c		16	40	μs
CKI				
Input Frequency - f_i	$\div 8$ Mode	0.2	0.5	MHz
Duty Cycle		30	60	%
Rise Time	$f_i = 0.5\text{ MHz}$		500	ns
Fall Time			200	ns
CKI Using RC ($\div 4$)	$R = 56\text{ k}\Omega \pm 5\%$ $C = 100\text{ pF} \pm 10\%$			
Instruction Cycle Time (Note 1)		16	28	μs
Inputs:				
G3-G0, L7-L0		8.0		μs
t_{SETUP}		1.3	1.3	μs
t_{HOLD}				
SI		2.0		μs
t_{SETUP}		1.0		μs
t_{HOLD}				
Output Propagation Delay	Test Condition: $C_L = 50\text{ pF}$, $R_L = 20\text{ k}\Omega$, $V_{\text{OUT}} = 1.5\text{V}$			
SO, SK Outputs			4.0	μs
tpd1 , tpd0				
All Other Outputs				
tpd1 , tpd0			5.6	μs

Note 1: Variation due to the device included.

Connection Diagram

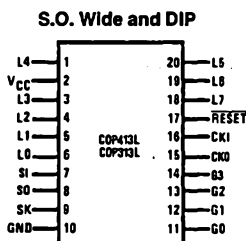


FIGURE 2

TL/DD/8371-2

Order Number COP313L-XXX/D or COP413L-XXX/D
 See NS Hermetic Package Number D20A

Order Number COP313L-XXX/W or
 COP413L-XXX/W
 See NS Surface Mount Package Number M20B

Order Number COP313L-XXX/N or COP413L-XXX/N
 See NS Molded Package Number N20A

Pin Descriptions

Pin	Description
L7-L0	8-bit bidirectional I/O port
G3-G0	4-bit bidirectional I/O port
SI	Serial input (or counter input)
SO	Serial output (or general purpose output)
SK	Logic-controlled clock (or general purpose output)
CKI	System oscillator input
CKO	System oscillator output or NC
RESET	System reset input
V _{CC}	Power Supply
GND	Ground

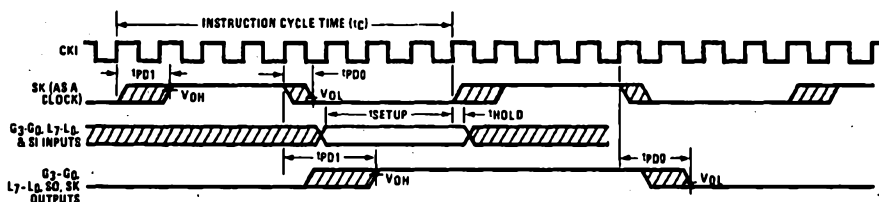


FIGURE 3. Input/Output Timing Diagrams (Ceramic Resonator Divide-by-8 Mode)

TL/DD/8371-3

Functional Description

A block diagram of the COP413L is given in *Figure 1*. Data paths are illustrated in simplified form to depict how the various logic elements communicate with each other in implementing the instruction set of the device. Positive logic is used. When a bit is set, it is a logic "1" (greater than 2V). When a bit is reset, it is a logic "0" (less than 0.8V).

All functional references to the COP413L also apply to the COP313L.

PROGRAM MEMORY

Program Memory consists of a 512-byte ROM. As can be seen by an examination of the COP413L instruction set, these words may be program instructions, program data, or ROM addressing data. Because of the special characteristics associated with the JP, JSRP, JID and LQID instructions, ROM must often be thought of as being organized into 8 pages of 64 words each.

ROM addressing is accomplished by a 9-bit PC register. Its binary value selects one of the 512 8-bit words contained in ROM. A new address is loaded into the PC register during each instruction cycle. Unless the instruction is a transfer of control instruction, the PC register is loaded with the next sequential 9-bit binary count value. Two levels of subroutine nesting are implemented by the 9-bit subroutine save registers, SA and SB, providing a last-in, first out (LIFO) hardware subroutine stack.

ROM instruction words are fetched, decoded and executed by the Instruction Decode, Control and Skip Logic circuitry.

DATA MEMORY

Data memory consists of a 128-bit RAM, organized as 4 data registers of 8 4-bit digits. RAM addressing is implemented by a 6-bit B register whose upper 2 bits (Br) select 1 of 4 data registers and lower 3 bits of the 4-bit Bd select 1 of 8 4-bit digits in the selected data register. While the 4-bit contents of the selected RAM digit (M) is usually loaded into or from, or exchanged with, the A register (accumulator), it may also be loaded into the Q latches or loaded from the L ports. RAM addressing may also be performed directly by the XAD 3, 15 instruction.

The most significant bit of Bd is not used to select a RAM digit. Hence each physical digit of RAM may be selected by two different values of Bd as shown in *Figure 4* below. The skip condition for XIS and XDS instructions will be true if Bd changes between 0 and 15, but NOT between 7 and 8 (see Table III).

INTERNAL LOGIC

The 4-bit A register (accumulator) is the source and destination register for most I/O, arithmetic, logic and data memory access operations. It can also be used to load the Bd portion of the B register, to load 4 bits of the 8-bit Q latch data, to input 4 bits of the 8-bit L I/O port data and to perform data exchanges with the SIO register.

A 4-bit adder performs the arithmetic and logic functions of the COP413L, storing its results in A. It also outputs a carry bit to the 1-bit C register, most often employed to indicate arithmetic overflow. The C register, in conjunction with the XAS instruction and the EN register, also serves to control the SK output. C can be outputted directly to SK or can enable SK to be a sync clock each instruction cycle time. (See XAS instruction and EN register description, below.)

The G register contents are outputs to 4 general purpose bidirectional I/O ports.

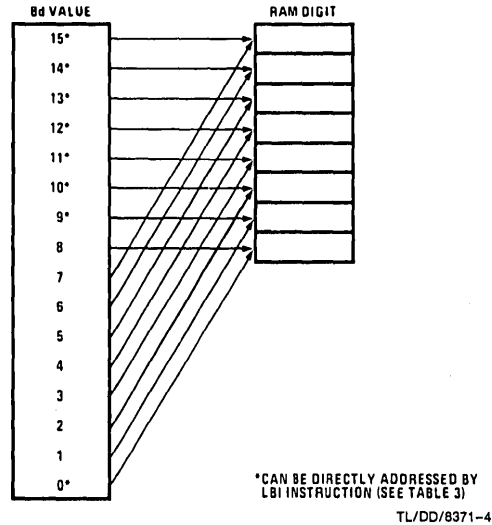


FIGURE 4. RAM Digit Address to Physical RAM Digit Mapping

The Q register is an internal, latched, 8-bit register, used to hold data loaded from M and A, as well as 8-bit data from ROM. Its contents are output to the L I/O ports when the L drivers are enabled under program control. (See LEI instruction.)

The 8 L drivers, when enabled, output the contents of latched Q data to the L I/O ports. Also, the contents of L may be read directly into A and M.

The SIO register functions as a 4-bit serial-in/serial-out shift register or as a binary counter depending on the contents of the EN register. (See EN register description, below.) Its contents can be exchanged with A, allowing it to input or output a continuous serial data stream. SIO may also be used to provide additional parallel I/O by connecting SO to external serial-in/parallel-out shift registers.

The XAS instruction copies C into the SKL Latch. In the counter mode, SK is the output of SKL in the shift register mode, SK outputs SKL ANDed with internal instruction cycle clock.

The EN register is an internal 4-bit register loaded under program control by the LEI instruction. The state of each bit of this register selects or deselects the particular feature associated with each bit of the EN register (EN₃–EN₀).

1. The least significant bit of the enable register, EN₀ selects the SIO register as either a 4-bit shift register or a 4-bit binary counter. With EN₀ set, SIO is an asynchronous binary counter, decrementing its value by one upon each low-going pulse ("1" to "0") occurring on the SI input. Each pulse must be at least two instruction cycles wide. SK outputs the value of SKL. The SO output is equal to the value of EN₃. With EN₀ reset, SIO is a serial shift register shifting with each instruction cycle time. The data present at SO goes into the least significant bit of SIO. SO can be enabled to output the most significant bit of SIO each cycle time. (See 4 below.) The SK output becomes a logic-controlled clock.
2. EN₁ is not used. It has no effect on COP413L operation.

Functional Description (Continued)

TABLE I. Enable Register Modes - Bits EN₃ and EN₀

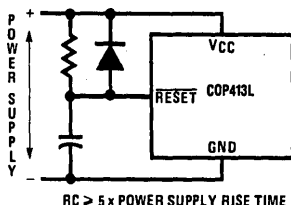
EN ₃	EN ₀	SIO	SI	SO	SK
0	0	Shift Register	Input to Shift Register	0	If SKL = 1, SK = Clock If SKL = 0, SK = 0
1	0	Shift Register	Input to Shift Register	Serial Out	If SKL = 1, SK = Clock If SKL = 0, SK = 0
0	1	Binary Counter	Input to Binary Counter	0	If SKL = 1, SK = 1 If SKL = 0, SK = 0
1	1	Binary Counter	Input to Binary Counter	1	If SKL = 1, SK = 1 If SKL = 0, SK = 0

3. With EN₂ set, the L drivers are enabled to output the data in Q to the L I/O ports. Resetting EN₂ disables the L drivers, placing the L I/O ports in a high impedance input state.

4. EN₃, in conjunction with EN₀, affects the SO output. With EN₀ set (binary counter option selected) SO will output the value loaded into EN₃. With EN₀ reset (serial shift register option selected), setting EN₃ enables SO as the output of the SIO shift register, outputting serial shifted data each instruction time. Resetting EN₃ with the serial shift register option selected disables SO as the shift register output; data continues to be shifted through SIO and can be exchanged with A via an XAS instruction but SO remains reset to "0". Table I provides a summary of the modes associated with EN₃ and EN₀.

INITIALIZATION

The Reset Logic will initialize (clear) the device upon power-up if the power supply rise time is less than 1 ms and greater than 1 μ s. If the power supply rise time is greater than 1 ms, the user must provide an external RC network and diode to the RESET pin as shown below (Figure 5). The RESET pin is configured as a Schmitt trigger input. If not used it should be connected to V_{CC}. Initialization will occur whenever a logic "0" is applied to the RESET input, provided it stays low for at least three instruction cycle times.

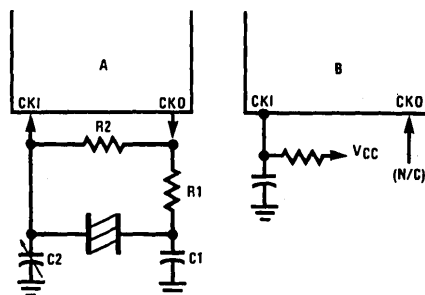

FIGURE 5. Power-Up Clear Circuit

Upon initialization, the PC register is cleared to 0 (ROM address 0) and the A, B, C, EN, and G registers are cleared. The SK output is enabled as a SYNC output, providing a pulse each instruction cycle time. *Data Memory (RAM) is not cleared upon initialization.* The first instruction at address 0 must be a CLRA.

OSCILLATOR

There are two basic clock oscillator configurations available as shown by Figure 6.

- Resonator Controlled Oscillator. CKI and CKO are connected to an external ceramic resonator. The instruction cycle frequency equals the resonator frequency divided by 8.
- RC Controlled Oscillator. CKI is configured as a single pin RC controlled Schmitt trigger oscillator. The instruction cycle equals the oscillation frequency divided by 4. CKO becomes no connection.



TL/DD/8371-6

FIGURE 6. COP413L Oscillator

Ceramic Resonator Oscillator

Resonator Value	Component Values			
	R1 (Ω)	R2 (Ω)	C1 (pF)	C2 (pF)
455 kHz	4.7k	1M	220	220

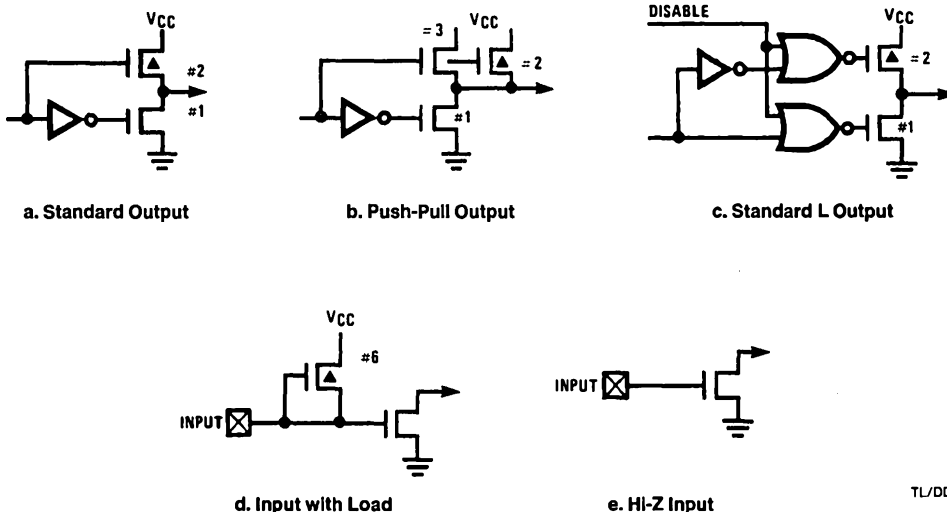
RC Controlled Oscillator

R (k Ω)	C (pF)	Instruction Cycle Time (n μ s)
51	100	19 \pm 15%
82	56	19 \pm 13%

Note: 200 k Ω \geq R \geq 25 k Ω

220 pF \geq C \geq 50 pF

Functional Description (Continued)



TL/DD/8371-7

FIGURE 7. Input and Output Configurations

I/O CONFIGURATIONS

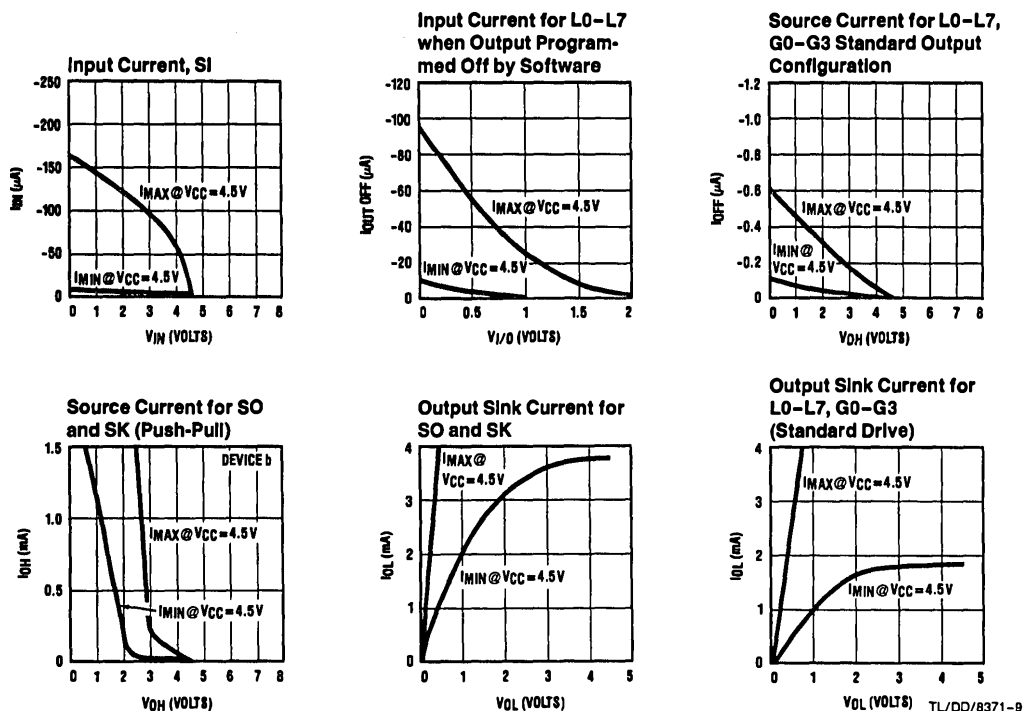
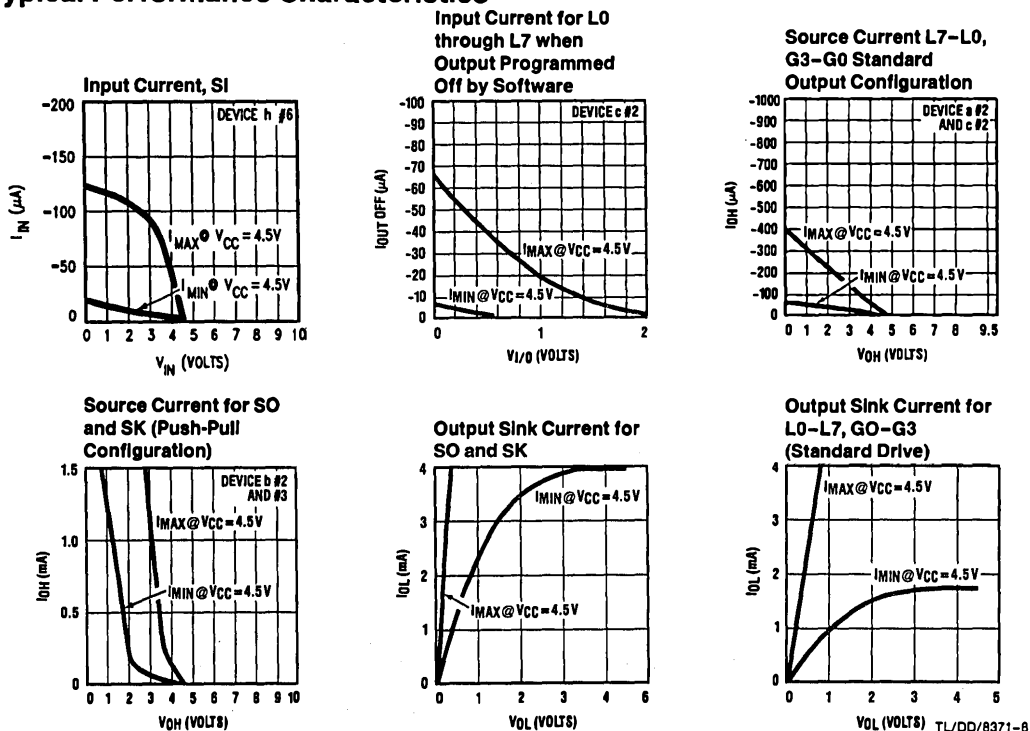
COP413L inputs and outputs have the following configurations, illustrated in *Figure 7*:

- a. G0–G3—an enhancement mode device to ground in conjunction with a depletion-mode device to V_{CC} .
- b. SO, SK—an enhancement mode device to ground in conjunction with a depletion-mode device paralleled by an

enhancement-mode device to V_{CC} . This configuration has been provided to allow for fast rise and fall times when driving capacitive loads.

- c. L0–L7—same as a., but may be disabled.
- d. SI has on-chip depletion load device to V_{CC} .
- e. RESET has a Hi-Z input which must be driven to a "1" or "0" by external components.

Typical Performance Characteristics



COP413L Instruction Set

Table II is a symbol table providing internal architecture, instruction operand and operational symbols used in the instruction set table. Table III provides the mnemonic, oper-

and, machine code data flow, skip conditions and description associated with each instruction in the COP413L instruction set.

TABLE II. COP413L Instruction Set Table Symbols

Symbol	Definition
Internal Architecture Symbols	
A	4-bit Accumulator
B	6-bit RAM Address Register
Br	Upper 2 bits of B (register address)
Bd	Lower 4 bits of B (digit address)
C	1-bit Carry Register
EN	4-bit Enable Register
G	4-bit Register to latch data for G I/O Port
L	8-bit TRI-STATE® I/O Port
M	4-bit contents of RAM Memory pointed to by B Register
PC	9-bit ROM Address Register (program counter)
Q	8-bit Register to latch data for L I/O Port
SA	9-bit Subroutine Save Register A
SB	9-bit Subroutine Save Register B
SIO	4-bit Shift Register and Counter
SK	Logic Controlled Clock Output
Instruction Operand Symbols	
d	4-bit Operand Field, 0–15 binary (RAM Digit Select)
r	2-bit Operand Field, 0–3 binary (RAM Register Select)
a	9-bit Operand Field, 0–511 binary (ROM Address)
y	4-bit Operand Field, 0–15 binary (Immediate Data)
RAM(s)	Contents of RAM location addressed by s
ROM(t)	Contents of ROM location addressed by t
Operational Symbols	
+	Plus
–	Minus
→	Replaces
↔	Is exchanged with
=	Is equal to
\bar{A}	The one's complement of A
⊕	Exclusive-OR
:	Range of values

COP413L Instruction Set (Continued)

TABLE III. COP413L Instruction Set

Mnemonic	Operand	Hex Code	Machine Language Code (Binary)	Data Flow	Skip Conditions	Description
ARITHMETIC INSTRUCTIONS						
ASC		30	0011 0000	$A + C + \text{RAM}(B) \rightarrow A$ Carry $\rightarrow C$	Carry	Add with Carry, Skip on Carry
ADD		31	0011 0001	$A + \text{RAM}(B) \rightarrow A$	None	Add RAM to A
AISC	y	5-	0101 y	$A + y \rightarrow A$	Carry	Add Immediate, Skip on Carry ($y \neq 0$)
CLRA		00	0000 0000	$0 \rightarrow A$	None	Clear A
COMP		40	0100 0000	$\bar{A} \rightarrow A$	None	One's complement of A to A
NOP		44	0100 0100	None	None	No Operation
RC		32	0011 0010	"0" $\rightarrow C$	None	Reset C
SC		22	0010 0010	"1" $\rightarrow C$	None	Set C
XOR		02	0000 0010	$A \oplus \text{RAM}(B) \rightarrow A$	None	Exclusive-OR RAM with A
TRANSFER OF CONTROL INSTRUCTIONS						
JID		FF	1111 1111	$\text{ROM}(\text{PC}_8, A, M) \rightarrow \text{PC}_{7:0}$	None	Jump Indirect (Note 2)
JMP	a	6-	0110 000 a ₉	$a \rightarrow \text{PC}$	None	Jump
JP	a	-	1 a _{6:0}	$a \rightarrow \text{PC}_{6:0}$	None	Jump within-Page (Note 3)
		-	11 a _{5:0}	$a \rightarrow \text{PC}_{5:0}$		
		-	10 a _{5:0}			
JSRP	a	-	0110 100 a ₈	$\text{PC} + 1 \rightarrow \text{SA} \rightarrow \text{SB}$ $010 \rightarrow \text{PC}_{8:6}$ $a \rightarrow \text{PC}_{5:0}$	None	Jump to Subroutine Page (Note 4)
JSR	a	6-	0110 100 a ₈	$\text{PC} + 1 \rightarrow \text{SA} \rightarrow \text{SB}$ $a \rightarrow \text{PC}$	None	Jump to Subroutine
RET		48	0100 1000	$\text{SB} \rightarrow \text{SA} \rightarrow \text{PC}$	None	Return from Subroutine
RETSK		49	0100 1001	$\text{SB} \rightarrow \text{SA} \rightarrow \text{PC}$	Always Skip on Return	Return from Subroutine then Skip
MEMORY REFERENCE INSTRUCTIONS						
CAMQ		33	0011 0011	$A \rightarrow Q_{7:4}$	None	Copy A, RAM to Q
		3C	0011 1100	$\text{RAM}(B) \rightarrow Q_{3:0}$		
LD	r	-5	00 r 0101	$\text{RAM}(B) \rightarrow A$ $\text{Br} \oplus r \rightarrow \text{Br}$	None	Load RAM into A, Exclusive-OR Br with r
LQID		BF	1011 1111	$\text{ROM}(\text{PC}_8, A, M) \rightarrow Q$ $\text{SA} \rightarrow \text{SB}$	None	Load Q Indirect (Note 2)
RMB	0	4C	0100 1100	$0 \rightarrow \text{RAM}(B)_0$	None	Reset RAM Bit
	1	45	0100 0101	$0 \rightarrow \text{RAM}(B)_1$		
	2	42	0100 0010	$0 \rightarrow \text{RAM}(B)_2$		
	3	43	0100 0011	$0 \rightarrow \text{RAM}(B)_3$		
SMB	0	4D	0100 1101	$1 \rightarrow \text{RAM}(B)_0$	None	Set RAM Bit
	1	47	0100 0111	$1 \rightarrow \text{RAM}(B)_1$		
	2	46	0100 0110	$1 \rightarrow \text{RAM}(B)_2$		
	3	4B	0100 1011	$1 \rightarrow \text{RAM}(B)_3$		

COP413L Instruction Set (Continued)**TABLE III. COP413L Instruction Set** (Continued)

Mnemonic	Operand	Hex Code	Machine Language Code (Binary)	Data Flow	Skip Conditions	Description
MEMORY REFERENCE INSTRUCTIONS (Continued)						
STII	y	7-	<u>0111</u> <u>y</u>	y → RAM(B) Bd + 1 → Bd	None	Store Memory Immediate and Increment Bd
X	r	-6	<u>00</u> <u>r</u> <u>0110</u>	RAM(B) ↔ A Br ⊕ r → Br	None	Exchange RAM with A, Exclusive-OR Br with r
XAD	3,15	23 BF	<u>0010</u> <u>0011</u> <u>1011</u> <u>1111</u>	RAM(3,15) ↔ A	None	Exchange A with RAM (3,15)
XDS	r	-7	<u>00</u> <u>r</u> <u>0111</u>	RAM(B) ↔ A Bd - 1 → Bd Br ⊕ r → Br	Bd decrements past 0	Exchange RAM with A and Decrement Bd. Exclusive-OR Br with r
XIS	r	-4	<u>00</u> <u>r</u> <u>0100</u>	RAM(B) ↔ A Bd + 1 → Bd Br ⊕ r → Br	Bd increments past 15	Exchange RAM with A and Increment Bd, Exclusive-OR Br with r
REGISTER REFERENCE INSTRUCTIONS						
CAB		50	<u>0101</u> <u>0000</u>	A → Bd	None	Copy A to Bd
CBA		4E	<u>0100</u> <u>1110</u>	Bd → A	None	Copy Bd to A
LBi	r,d	-	<u>00</u> <u>r</u> <u>(d-1)</u> (d = 0,9:15)	r,d → B	Skip until not a LBi	Load B immediate with r,d (Note 5)
LEI	y	33 6-	<u>0011</u> <u>0011</u> <u>0110</u> <u>y</u>	y → EN	None	Load EN Immediate (Note 6)
TEST INSTRUCTIONS						
SKC		20	<u>0010</u> <u>0000</u>		C = "1"	Skip if C is True
SKE		21	<u>0010</u> <u>0001</u>		A = RAM(B)	Skip if A Equals RAM
SKGZ		33	<u>0011</u> <u>0011</u>		G _{3:0} = 0	Skip if G is Zero (all 4 bits)
SKGBZ		21	<u>0010</u> <u>0001</u>			Skip if G Bit is Zero
	0	01	<u>0000</u> <u>0001</u>	1st byte	G ₀ = 0	
	1	11	<u>0001</u> <u>0001</u>	} 2nd byte	G ₁ = 0	
	2	03	<u>0000</u> <u>0011</u>		G ₂ = 0	
	3	13	<u>0001</u> <u>0011</u>		G ₃ = 0	
SKMBZ	0	01	<u>0000</u> <u>0001</u>		RAM(B) ₀ = 0	Skip if RAM Bit is Zero
	1	11	<u>0001</u> <u>0001</u>		RAM(B) ₁ = 0	
	2	03	<u>0000</u> <u>0011</u>		RAM(B) ₂ = 0	
	3	13	<u>0001</u> <u>0011</u>		RAM(B) ₃ = 0	

COP413L Instruction Set (Continued)**TABLE III. COP413L Instruction Set (Continued)**

Machine Language Code			Data Flow	Skip Conditions	Description	
Mnemonic	Operand	Hex Code (Binary)				
INPUT/OUTPUT INSTRUCTIONS						
ING		33	0011 0011	G → A	None	Input G Ports to A
		2A	0010 1010			
INL		33	0011 0011	L _{7:4} → RAM(B) L _{3:0} → A	None	Input L Ports to RAM, A
		2E	0010 1110			
OMG		33	0011 0011	RAM(B) → G	None	Output RAM to G Ports
		3A	0011 1010			
XAS		4F	0100 1111	A ↔ SIO, C → SKL	None	Exchange A with SIO (Note 2)

Note 1: All subscripts for alphabetical symbols indicate bit numbers unless explicitly defined (e.g., Br and Bd are explicitly defined) Bits are numbered 0 to N where 0 signifies the least significant bit (low-order, right-most bit). For example, A₃ indicates the most significant (left-most) bit of the 4-bit A register.

Note 2: For additional information on the operation of the XAS, JID, and LQID instructions, see below.

Note 3: The JP instruction allows a jump, while in subroutine pages 2 or 3, to any ROM location within the two-page boundary of pages 2 or 3. The JP instruction, otherwise, permits a jump to a ROM location within the current 64-word page. JP may not jump to the last word of a page.

Note 4: A JSRP transfers program control to subroutine page 2 (0010 is loaded into the upper 4 bits of P). A JSRP may not be used when in pages 2 or 3. JSRP may not jump to the last word in page 2.

Note 5: The machine code for the lower 4 bits of the LBI instruction equals the binary value of the "d" data *minus 1* e.g., to load the lower four bits of B (Bd) with the value 9 (1001₂), the lower 4 bits of the LBI instruction equal 8 (1000₂). To load 0, the lower 4 bits of the LBI instruction should equal 15 (1111₂).

Note 6: Machine code for operand field y for LEI instruction should equal the binary value to be latched into EN, where a "1" or "0" in each bit of EN corresponds with the selection or deselection of a particular function associated with each bit. (See Functional Description EN Register.)

Description of Selected Instructions

The following information is provided to assist the user in understanding the operation of several unique instructions and to provide notes useful to programmers in writing COP413L programs.

XAS INSTRUCTION

XAS (Exchange A with SIO) exchanges the 4-bit contents of the accumulator with the 4-bit contents of the SIO register. The contents of SIO will contain serial-in/serial-out shift register or binary counter data, depending on the value of the EN register. An XAS instruction will also affect the SK output. (See Functional Description, EN Register, above.) If SIO is selected as a shift register, an XAS instruction must be performed once every 4 instruction cycles to effect a continuous data stream.

JID INSTRUCTION

JID (Jump Indirect) is an indirect addressing instruction, transferring program control to a new ROM location pointed to indirectly by A and M. It loads the lower 8 bits of the ROM address register PC with the *contents* of ROM addressed by the 9-bit word, PC₈, A, M. PC₈ is not affected by this instruction.

Note that JID requires 2 instruction cycles to execute.

LQID INSTRUCTION

LQID (Load Q Indirect) loads the 8-bit Q register with the contents of ROM pointed to by the 9-bit word PC₈, A, M. LQID can be used for table lookup or code conversion such as BCD to seven-segment. The LQID instruction "pushes" the stack (PC + 1 → SA → SB) and replaces the least significant 8 bits of PC as follows: A → PC_{7:4}, RAM (B)

→ PC_{3:0}, leaving PC₈ unchanged. The ROM data pointed to by the new address is fetched and loaded into the Q latches. Next, the stack is "popped" (SB → SA → PC), restoring the saved value of PC to continue sequential program execution. Since LQID pushes SA → SB, the previous contents of SB are lost. Also, when LQID pops the stack, the previously pushed contents of SA are left in SB. The net result is that the contents of SA are placed in SB (SA → SB). Note that LQID takes two instruction cycle times to execute.

INSTRUCTION SET NOTES

- The first word of a COP413L program (ROM address 0) must be a CLRA (Clear A) instruction.
- Although skipped instructions are not executed, one instruction cycle time is devoted to skipping each byte of the skipped instruction. Thus all program paths except JID and LQID take the same number of cycle times whether instructions are skipped or executed. JID and LQID instructions take 2 cycles if executed and 1 cycle if skipped.
- The ROM is organized into 8 pages of 64 words each. The Program Counter is a 9-bit binary counter, and will count through page boundaries. If a JP, JSRP, JID or LQID instruction is located in the last word of a page, the instruction operates as if it were in the next page. For example: a JP located in the last word of a page will jump to a location in the next page. Also, a LQID or JID located in the last word of page 3 or will access data in the next group of 4 pages.

Description of Selected Instructions (Continued)

TEST MODE (NON-STANDARD OPERATION)

The SO output has been configured to provide for standard test procedures for the custom-programmable COP413L. With SO forced to logic "1", two test modes are provided, depending upon the value of SI:

- a. RAM and internal Logic Test Mode (SI = 1)
- b. ROM Test Mode (SI = 0)

These special test modes should not be employed by the user; they are intended for manufacturing test only.

Option List

The option selected must be sent in with the EPROM of ROM Code for a Mask order of 413L. Make xerox copy of the table, select the appropriate option, and send it in with the EPROM.

COP 413L/COP 313L

Option 1: Oscillator Selection

- = 0 Ceramic Resonator or external input frequency divided by 8. CKO is oscillator output.
- = 1 Single pin RC controlled oscillator divided by 4. CKO is no connection.

NOTE:

The following option information is to be sent to National along with the EPROM

Option 1: Value = _____ is: Oscillator Selection